	L #	Hits	EAST Search Text	DBs	Time Stamp	Type
1	L1	718	(356/237.3-237.5).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 12:50	IS&R
2	L2	1349	(382/144-149).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 12:50	IS&R
3	L3	649	(348/125,126,128).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 12:50	IS&R
4	L4	37988	("700").CLAS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 12:50	IS&R
5	L5	78	(L1 OR L2 OR L3) AND L4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 14:41	BRS
6	L6	14	("4541115" | "4817175" | "5384463" | "5430292" | "5557105" | "5699447" | "5799111" | "5825482" | "5892224" | "6031607" | "6252412" | "6465783" | "6538248" |	USPAT	2004/08/06 13:06	BRS
7	L7	19	(L1 OR L2 OR L3) AND wafer WITH fragment$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 14:58	BRS
8	L8	117406	(camera OR image OR video OR picture OR photo OR photograph) WITH (merg$3 OR combin$3 OR join$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 14:58	BRS
9	L9	381	(L1 OR L2 OR L3) AND L8	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 15:04	BRS
10	L10	0	(L1 OR L2 OR L3) AND (L8 SAME (cyclical OR recycl$3 OR recirculat$3) WITH (memory OR storage OR log OR buffer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 15:00	BRS
11	L11	1	(L1 OR L2 OR L3) AND L8 AND ((cyclical OR recycl$3 OR recirculat$3) WITH (memory OR storage OR log OR buffer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 15:00	BRS
12	L12	125	(L1 OR L2 OR L3) AND L8 SAME (memory OR stor$3 OR log$4 OR buffer$4 OR register$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 15:05	BRS
13	L13	0	6124926.URPN.	USPAT	2004/08/06 15:18	BRS

09/686895

	1	Document ID	Source	Issue Date	Title	Current OR	Inventor	2	3	4 [1]	5
1	☒	US 6535628 B2	USPAT	20030318	Detection of wafer fragments in a wafer processing apparatus	382/149	Smargiassi, Eugene et al.	☐	☐	☒	☐
2	☒	US 2001004375 A1	US-PGPUB	20011122	DETECTION OF WAFER FRAGMENTS IN A WAFER PROCESSING	382/149	SMARGIASSI, EUGENE et al.	☐	☐	☒	☐
3	☐	US 5659630 A	USPAT	19970819	Advanced manufacturing inspection system	382/149	Forslund, Donald Charles	☒	☐	☒	☐
4	☐	US 5644140 A	USPAT	19970701	Apparatus for checking semiconductor wafers with complementary light sources and two cameras	250/559.08	Biedermann, Ernst et al.	☒	☐	☒	☐
5	☒	US 6738506 B2	USPAT	20040518	Image processing system for multi-beam inspection	382/151	Miller, S. Daniel et al.	☐	☐	☒	☐
6	☐	US 6701002 B1	USPAT	20040302	Test method for image pickup devices	382/145	Karube, Koji	☒	☐	☒	☐
7	☐	US 6546308 B2	USPAT	20030408	Method and system for manufacturing semiconductor devices, and method and system for inspecting semiconductor devices	700/121	Takagi, Yuji et al.	☒	☐	☒	☐
8	☐	US 6535776 B1	USPAT	20030318	Method for localizing and isolating an errant process step	700/110	Tobin, Jr., Kenneth W. et al.	☒	☐	☒	☐
9	☐	US 6438438 B1	USPAT	20020820	Method and system for manufacturing semiconductor devices, and method and system for inspecting semiconductor devices	700/121	Takagi, Yuji et al.	☒	☐	☒	☐
10	☐	US 6198982 B1	USPAT	20010306	Method and apparatus for detecting the presence of particles on a wafer holder of semiconductor exposure equipment	700/121	Park, Soon-jong et al.	☒	☐	☒	☐
11	☐	US 5878151 A	USPAT	19990302	Moving object tracking	382/103	Tang, Qing et al.	☒	☐	☒	☐
12	☐	US 6721045 B1	USPAT	20040413	Method and apparatus to provide embedded substrate process monitoring through consolidation of multiple process inspection techniques	356/237.5	Hunter, Reginald	☒	☐	☒	☐
13	☐	US 6707545 B1	USPAT	20040316	Optical signal routing method and apparatus providing multiple inspection collection points on semiconductor	356/237.5	Hunter, Reginald	☒	☐	☒	☐
14	☐	US 6707544 B1	USPAT	20040316	Particle detection and embedded vision system to enhance substrate yield and throughput	356/237.5	Hunter, Reginald et al.	☒	☐	☒	☐
15	☐	US 6697517 B1	USPAT	20040224	Particle detection and embedded vision system to enhance substrate yield and throughput	382/149	Hunter, Reginald	☒	☐	☒	☐

	1	Document ID	Source	Issue Date	Title	Current OR	Inventor	2	3	4 [1]	5
16	☐	US 6693708 B1	USPAT	20040217	Method and apparatus for substrate surface inspection using spectral profiling techniques	356/237.5	Hunter, Reginald	☒	☐	☒	☐
17	☐	US 6630995 B1	USPAT	20031007	Method and apparatus for embedded substrate and system status monitoring	356/237.5	Hunter, Reginald	☒	☐	☒	☐
18	☐	US 6760471 B1	USPAT	20040706	Compensation system and related techniques for use in a printed circuit board inspection system	382/147	Raymond, Douglas W.	☒	☐	☒	☐
19	☒	US 6124926 A	USPAT	20000926	Defect detecting method and device	356/237.4	Ogawa, Tomoya et al.	☐	☐	☒	☐